

L Number	Hits	Search Text	DB	Time stamp
1	3537605	carrier board substrate pcb ((printed circuit) adj3 board)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:49
2	118072	ground same (carrier board substrate pcb ((printed circuit) adj3 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:50
3	506033	heat with (sink element radiate radiating dissipate dissipating element metal slug)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:50
4	775605	(through hole via) with (carrier board substrate pcb ((printed circuit) adj3 board))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:52
5	626538	(ground same (carrier board substrate pcb ((printed circuit) adj3 board))) ame (heat with (sink element radiate radiating dissipate dissipating element metal slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:52
6	783	((through hole via) with (carrier board substrate pcb ((printed circuit) adj3 board))) same (ground same (carrier board substrate pcb ((printed circuit) adj3 board))) same (heat with (sink element radiate radiating dissipate dissipating element metal slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:55
7	644	(chip die semiconductor dice Ic (integrated adj circuit)) and (((through hole via) with (carrier board substrate pcb ((printed circuit) adj3 board))) same (ground same (carrier board substrate pcb ((printed circuit) adj3 board))) same (heat with (sink element radiate radiating dissipate dissipating element metal slug)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 00:56
8	392	((chip die semiconductor dice Ic (integrated adj circuit)) and (((through hole via) with (carrier board substrate pcb ((printed circuit) adj3 board))) same (ground same (carrier board substrate pcb ((printed circuit) adj3 board))) same (heat with (sink element radiate radiating dissipate dissipating element metal slug)))) and (wire wiring)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 01:14
9	392	((chip die semiconductor dice Ic (integrated adj circuit)) and (((through hole via) with (carrier board substrate pcb ((printed circuit) adj3 board))) same (ground same (carrier board substrate pcb ((printed circuit) adj3 board))) same (heat with (sink element radiate radiating dissipate dissipating element metal slug)))) and (wire wiring)) and (heat with (sink element radiate radiating dissipate dissipating element metal slug))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2004/05/25 01:14